

REV.	ECN.	NO.	APPD.
A	BC-08-7035761	C.C. Huang	
B	BC-10-0117185	Gwo-Dah Lin	
C	BC-13-0084937	Davy Bu	

NOTES:

1. ELECTRICAL CHARACTERISTICS:

- 1-1 CURRENT RATING: 1.1 A MIN. PER PIN, 30°C RISE ABOVE AMBIENT.
1-2 CONTACT RESISTANCE: 30 MILLIOHMS MAX. INITIAL,
50 MILLIOHMS MAX. AFTER TEST.
1-3 INSULATION RESISTANCE: 1000 MEGOHMS MIN..
1-4 DIELECTRICAL WITHSTAND VOLTAGE: 500 V AC MIN. AT SEA LEVEL.

2. MECHANICAL CHARACTERISTICS:

- 2-1 CONTACT INSERTION FORCE: 1.15 N MAX. PER CONTACT PAIR.
2-2 CONTACT REMOVAL FORCE: 0.15 N MIN. PER CONTACT PAIR.
2-3 DURABILITY: 50 MATING AND UNMATING CYCLES.
2-4 CONTACT RETENTION FORCE: 3.43 N MIN.

3. ENVIRONMENTAL CHARACTERISTICS:

- 3-1 OPERATING TEMPERATURE RANGE: -40°C TO +105°C .

4. RECOMMENDED PROCESS: IR REFLOW 245°C, 3~5 s

5. PLEASE CONTACT FOXCONN SALES REPRESENTATIVE TO VERIFY PRODUCTION DETAILS & AVAILABILITY

PROD. NO.: 2EG 5 ** * - D2DS - **

FIELD PRODUCT SERIES:
2EG= PCI EXPRESS

TERMINAL TYPE:
5= SMT TYPE

NO. OF POS.
18= 36 POSITIONS
32= 64 POSITIONS
49= 98 POSITIONS
82= 164 POSITIONS

PLATING TYPE:
4F: LEAD FREE
RoHS COMPLIANT

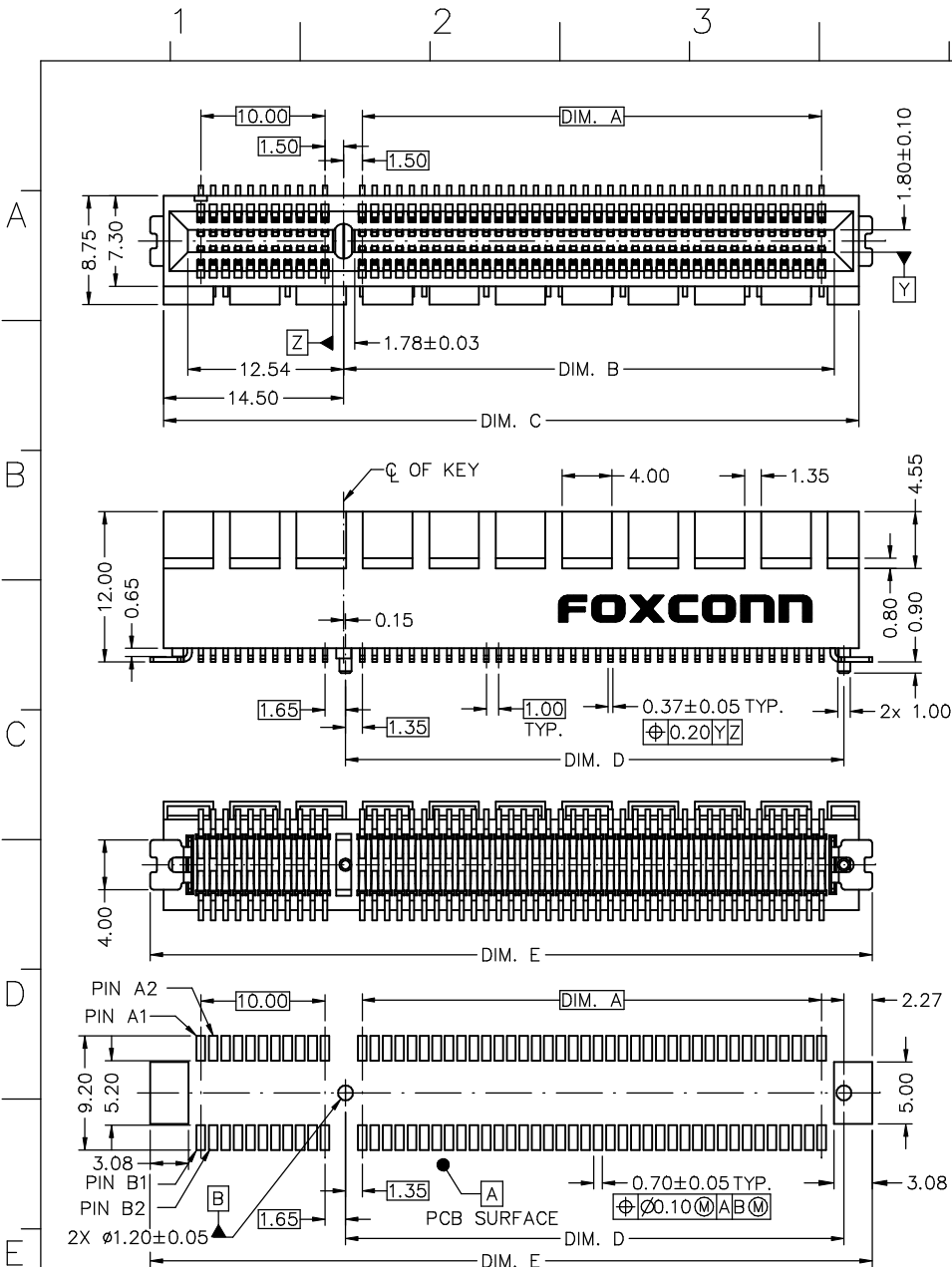
EXTENSION CODE

CONTACT AREA GOLD PLATING:

1= GOLD FLASH
7= 15u" GOLD
3= 30u" GOLD

TAIL :
9= FOR SMT

3	CONTACT	COPPY ALLOY	50u" NICKEL PLATING OVERALL UNDERPLATED. 100u" TIN PLATING OVER NICKEL AT TAIL. GOLD PLATING ON CONTACT AREA.
2	HOOK	COPPY ALLOY	50u" NICKEL PLATING OVERALL UNDERPLATED. 100u" TIN PLATING OVER NICKEL AT TAIL.
1	HOUSING	THERMOPLASTIC UL 94V-0	MOLDED BLACK
ITEM	DESCRIPTION	MATERIAL	TREATMENT
x.±	x.±	UNITS mm	NAME(INTENDED USE) SIOM SMT TYPE PCI EXPRESS CONN.
.x± 0.38	.x'±	MAT'L	
.xx± 0.25	.xx'±	N/A	PART NO.(INTENDED USE) 2EG5****-D2DS- **
.xxx±	.xxx'±	FINISH	APPD: Davy Bu 11/21'13
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		N/A	DR: Qin Teng 12/3'13
			DWG. NO.: 303-0000-1799
			SCALE SHEET REV. N/A 1/2 C

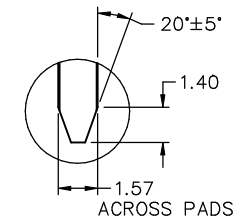
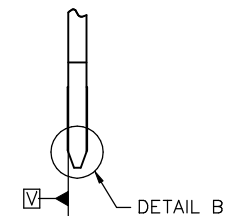
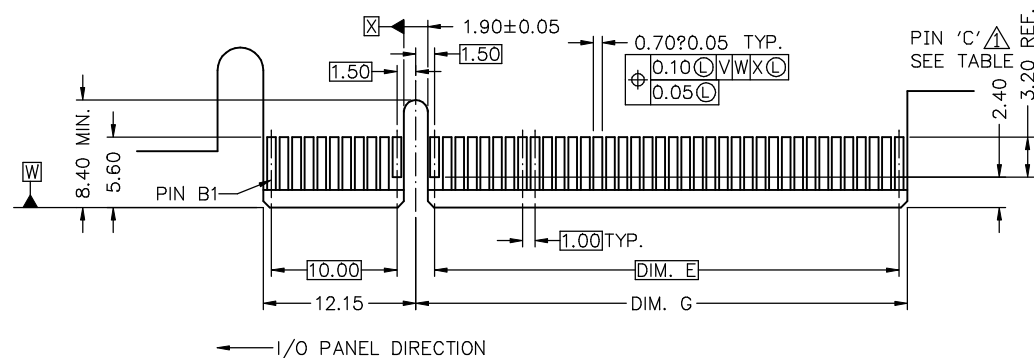


RECOMMENDED PCB LAYOUT

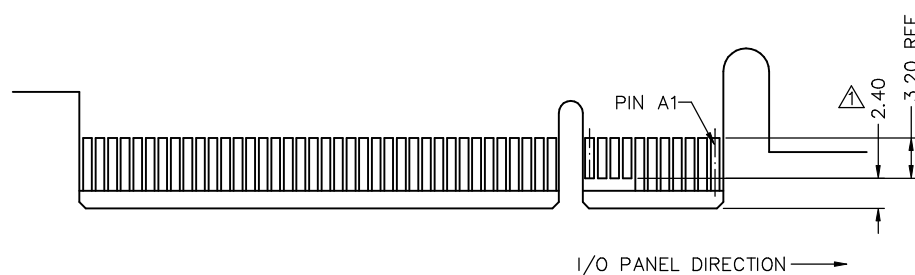
2EG582**-D2DS- **	70.00	72.54	89.00	73.15	91.15
2EG549**-D2DS- **	37.00	39.54	56.00	40.15	58.15
2EG532**-D2DS- **	20.00	22.54	39.00	23.15	41.15
2EG518**-D2DS- **	6.00	8.54	25.00	9.15	27.15
PART NUMBER	DIM. A	DIM. B	DIM. C	DIM. D	DIM. E

REV.	ECN.	NO.	APPD.

SEE SHEET 1/2



DETAIL B
SCALE 2:1



SECONDARY (SOLDER) SIDE

CONNECTOR LINK WIDTH	# POS REF	DIM. E	DIM. G	'C'
X1	36	6.00	8.15	A8,A9,A10,A11,B11,B12
X4	64	20.00	22.15	
X8	98	37.00	39.15	
X16	164	70.00	72.15	

ADD-IN CARD EDGE-FINGER DIMENSIONS

NOTES:

- NO TIE PERMITTED FROM CARD EDGE TO LEADING EDGE OF PAD FOR PINS A1 AND 'C'.
- CHAMFER EDGES MUST BE FREE OF CUTTING BURRS.

X.±	X.*±	UNITS	mm	NAME(INTENDED USE)	FOXCONN
.X± 0.38	.X*±	MAT'L		SIOM SMT TYPE	FOXCONN INTERCONNECT TECHNOLOGY LIMITED
.XX± 0.25	.XX*±	N/A		PCI EXPRESS CONN.	
.XXX±	.XXX*±	FINISH		PART NO.(INTENDED USE)	TITLE:
		N/A		2EG5****-D2DS-**	CUSTOMER DRAWING
		Q'TY		APPD: Davy Bu 11/21'13	DWG. NO.: 303-0000-1799
		N/A		CHKD: Tim Yao 12/3'13	
				DR: Qin Teng 12/3'13	
					SCALE SHEET REV.
					N/A 2/2 C

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